



IPC-2581B-WAM1

2016 - December

Generic Requirements for Printed Board Assembly Products Manufacturing Description Data and Transfer Methodology

Supersedes IPC-2581B
September 2013

An international standard developed by IPC

Association Connecting Electronics Industries



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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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Developed by Product Data Description (Laminar View) Subcommittee (2-16) of the Electronic Product Data Description Committee (2-10) of IPC

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Supersedes:

IPC-2581B - September 2013
IPC-2581A - May 2012
IPC-2581 with Amendment 1 -
May 2007
IPC-2581 - March 2004

Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Product Data Description (Laminar View) Subcommittee (2-16) of the Electronic Product Data Description Committee (2-10) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

Electronic Product Data Description Committee	Product Data Description (Laminar View) Subcommittee	Technical Liaison of the IPC Board of Directors
Chair Gary M. Ferrari FTG Circuits	Chair Karen McConnell Northrop Grumman Corporation	Bob Neves Microtek (Changzhou) Laboratories

Product Data Description (Laminar View) Subcommittee

Edward Acheson, Cadence Design Systems Inc.	Innovators, Ltd.	Hemant Shah, Cadence Design Systems Inc.
Craig Armenti, Zuken USA, Inc.	Ronny Kovartovsky, Frontline PCB Solutions	Chris Shaw, Fujitsu Network Communications
Kjell Asp, Ericsson AB	Kevin Kusiak, Lockheed Martin Space Systems Company	Rainer Taube, Taube Electronic GmbH
Jimmy Baccam, Lockheed Martin Missiles & Fire Control	Jeff Lewis, Holaday Circuits Inc.	Karel Tavernier, Ucamco
Robert Bagsby, Rockwell Collins	Humair Mandavia, Zuken USA, Inc.	Denise Turley, Fujitsu Network Communications
Tomas Bergsten, Ericsson AB	Jason Marsh, Nextflex	John Vaughn, Fujitsu Network Communications
Gary Carter	Karen McConnell, Northrop Grumman Corporation	Wenju Wang, Cadence Design Systems Inc.
Max Clark, Mentor Graphics Corporation	Kristopher Moyer, Aerojet Rocketdyne	Steve Watt, Zuken USA, Inc.
Joseph Clark, DownStream Technologies, LLC	William Newhard, DownStream Technologies, LLC	Jamie Wise, WISE Software Solutions Inc.
Amy Clements, Zuken USA, Inc.	Sheldon Parnes, Ansys	
Larry Frost, Sanmina Corporation	James Pierce, Axiom Electronics, LLC	
Terry Hoffman, Cisco Systems Inc.		
Satoshi Kojima, NEC Solution		

A special note of thanks goes to the following individuals for their dedication to bringing this project to fruition. We would like to highlight those individuals who made major contributions to the development of this standard.

Edward Acheson, Cadence Design Systems Inc.	Ronny Kovartovsky, Frontline PCB Solutions	Chris Shaw, Fujitsu Network Communications
Kent Balius, TTM Technologies	Humair Mandavia, Zuken USA, Inc.	John Vaughn, Fujitsu Network Communications
Tomas Bergsten, Ericsson AB	William Newhard, DownStream Technologies, LLC	Steve Watt, Zuken USA, Inc.
Gary Carter	James Pierce, Axiom Electronics, LLC	Jamie Wise, WISE Software Solutions Inc.
Joseph Clark, DownStream Technologies, LLC		
Terry Hoffman, Cisco Systems Inc.	Hemant Shah, Cadence Design Systems Inc.	

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